

SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG800480S32A-N-A0

Doc.Version:02

Customer Appro	oval:		
☐ Accept			☐ Reject
YEEBO	NAME	SIGNATURE	DATE
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Check	Mechanical Engineer	文建	2019/4/18
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Approval		碑底砖	2019.4.19
☐ APPROVAI	L FOR SPECIFICATIONS	ONLY	
APPROVAL	L FOR SPECIFICATIONS	AND SAMPLE	
			WIMRD005-02-D

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1. Revision History

Sample Version	DOC. Version	DATE		DESCRIPTION		
A0	00	2019-01-16	Spec Only	First issue	W.J.C/Z.J.Q	
A0	01	2019-01-22	Spec Only	Modify BacklightP13	W.J.C/Z.J.Q	
A0	02	2019-04-18	Full Spec	Modify BacklightP13 First Sample	W.J.C/Z.J.Q	

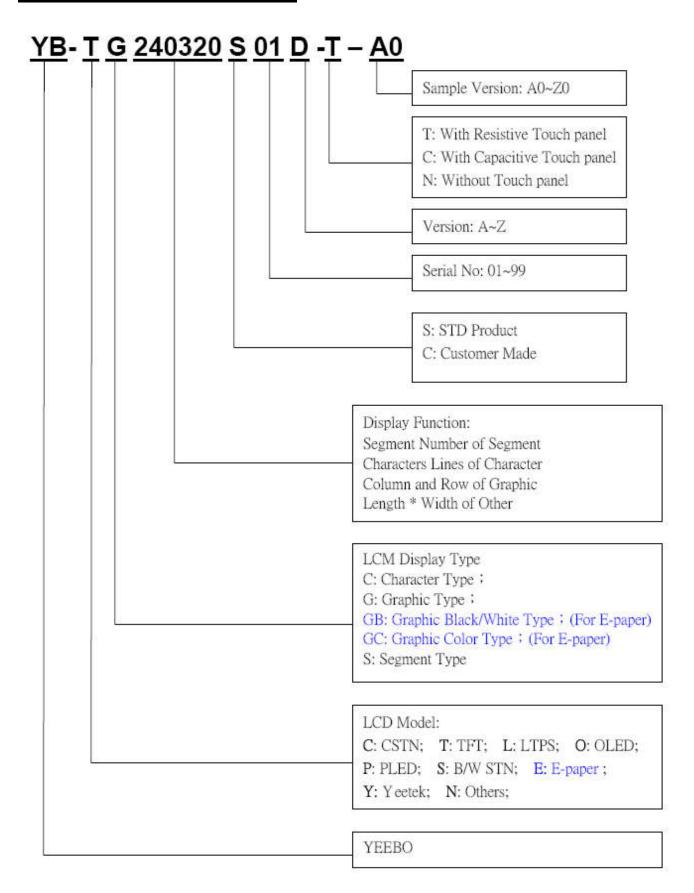


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3. Module Numbering System:



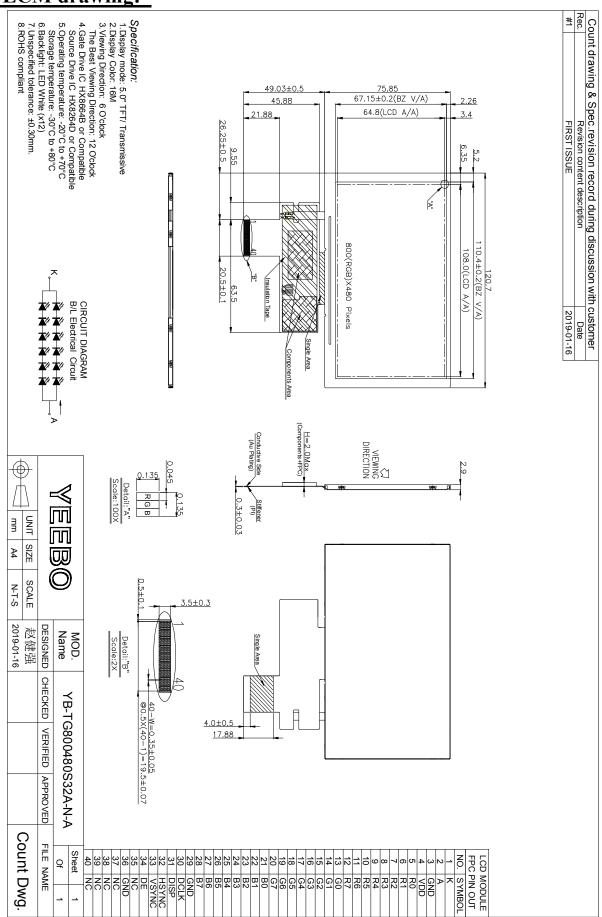


4. General Specification:

ITEM	CONTENTS
Module Size	120.7 (W) * 75.85(H) * 2.9(T) mm
Module Size(With FPC)	120.7(W) * 124.88(H) * 2.9(T) mm
Display Size	5.0 inch
Display Format	800(RGB)* 480 WVGA
Active Area	108.0(W) *64.8(H) mm
LCD Type	Active matrix TFT/ Transmissive
Input Data	24 bit RGB interface
Viewing Direction (Gray inversion)	6 O'clock
The Best Viewing Direction	12 O'clock
Source Drive IC	HX8264D or Compatible
Gate Drive IC	HX8664B or Compatible
Weight	53g



5. LCM drawing:





6. Electrical Characteristics:

6-1 Absolute Maximum Ratings

TFT IC HX8264D+HX8664B (Ta= 25° C)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Power Voltage	VDD	-0.5	-	+3.96	V	Note1 Note2
Operating Temperature	TOPR	-20	-	+70	${\mathbb C}$	Note1 Note2
Storage Temperature	TSTR	-30	-	+80	${\mathbb C}$	Note1 Note2

Note 1: The driver IC may be permanently damaged if it is used under the condition exceeding the above absolute maximum values. It is also recommended to use the driver IC within the limit of its electric characteristics during normal operation. Exceeding the conditions may lead to malfunction of it and affect its credibility.

Note 2: The voltage from GND.

6-2 Electrical Characteristics TFT IC HX8264D+HX8664B

(Ta=25°C)

Item	Symbol		Rating	Unit	Remark	
Item	Symbol	Min	Typ	Max	Ollit	Kelliaik
Power Voltage Logic	VDD	3.0	3.3	3.6	V	Note 1
`Input voltage L level	VIL	GND	-	0.3*VDD	V	VDD=3.0
Input voltage H level	VIH	0.7* VDD	-	VDD	V	~3.6V
LCD Drive Power current	ILCD	-	63	94.5	mA	VDD= 3.3V

Note1:

Vcom must be adjusted to optimize display quality: Cross-talk, Contrast Ratio and etc.

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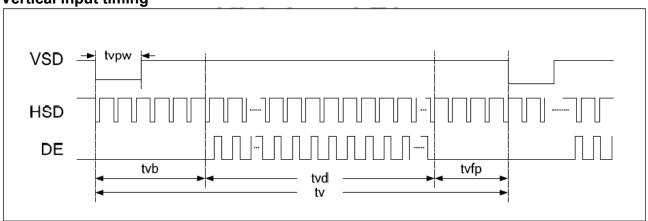
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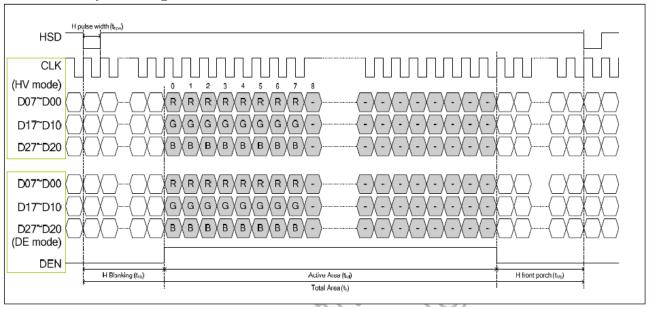
6-3 Timing Characteristics

6-3-1 TFT IC HX8264D+HX8664B Data Input Format

Vertical input timing



Horizontal input timing





6-3-2 TFT IC HX8264D+HX8664B Timing Conditions

Resolution: 800x480

Horizontal timing

Parameter	Cumbal		Unit			
Faranietei	Symbol	Min. Typ.		Max.	Onit	
Horizontal Display Area	thd		800	70	DCLK	
DCLK frequency	fclk) -	30	50	MHz	
One Horizontal Line	th	889	928	1143	DCLK	
HS pulse width	thpw	1	48	255	DCLK	
HS Back Porch (Blanking)	thb	7	88		DCLK	
HS Front Porch	thfp	1	40	255	DCLK	
DE mode Blanking	th-thd	85	128	512	DCLK	

Vertical timing

Parameter	Cumbal		Hnit			
Parameter	Symbol	Min. Typ.		Max.	Unit	
Vertical Display Area	tvd	- /	480		TH	
VS period time	tv	513	525	767	T _H	
VS pulse width	tvpw	3	3	255	T _H	
VS Back Porch (Blanking)	tvb	50	> 32 <	(())	T _H	
VS Front Porch	tvfp	(1)	13	255	T _H	
DE mode Blanking	tv-tvd	(4)	45 (255	T _H	

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7. Optical Characteristics:

14	Idom		Conditio Specificat		cification	ions		Note	
Item		Symbol	ns	Min	Тур	Max	Unit	Note	
Transmitt	tance	T(%)	_	4.0	4.3	-	%	-	
Contrast Ratio		CR	Θ=0 Normal Viewing angle	350	500	-		(1) (2)	
Response	time	TR+TF	_	-	25	-	ms	(1) (3)	
	Hor.	Өх+		-	65	-			
Viewing	1101.	О Σ-	CR≧10	-	65	-	deg.	(1)	
angle	Ver.	⊖у+	$O_{1} = 10$	-	50	-	ueg.	(1)	
	V CI.	Өу-		-	60	-			

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

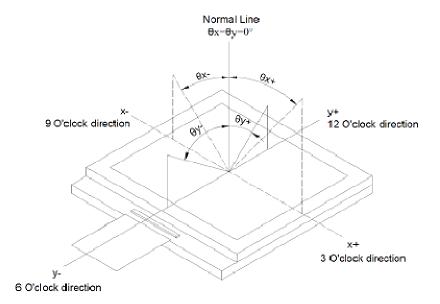
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	D 1	X		0.5408	0.5908	0.6408
	Red	y		0.2655	0.3155	0.3655
Chromaticity		X	0 1 00	0.2950	0.3450	0.3950
Coordinates	Green	y	$\theta = \phi = 0^{\circ}$ LED Backlight	0.4760	0.5260	0.5760
(Transmissive)	Blue	X		0.0967	0.1467	0.1967
		y		0.0399	0.0899	0.1399
	XX71 *4	X		0.2339	0.2839	0.3339
	White	у		0.2598	0.3098	0.3598



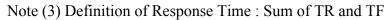
Note (1) Definition of Viewing Angle:

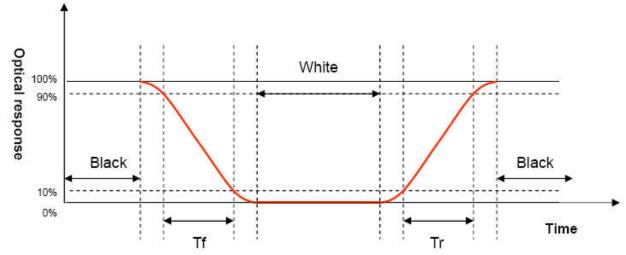


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black







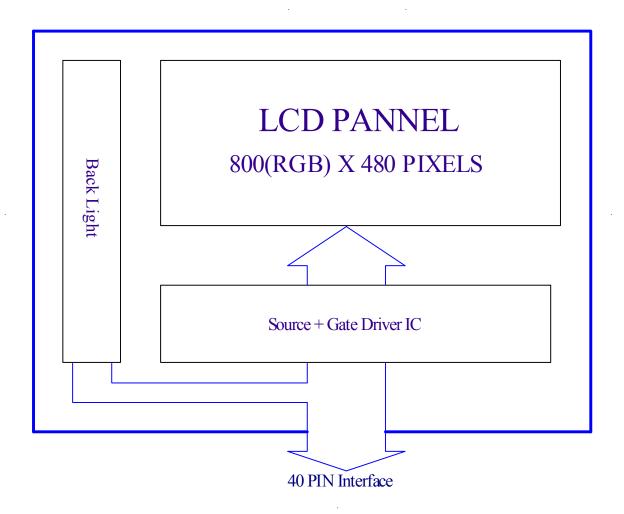
8. Interface Pin Assignment:

PIN NO.	Symbol	I/O	Description
1	K	Р	Power for LED backlight cathode
2	Α	Р	Power for LED backlight anode
3	GND	Р	Power ground
4	VDD	Р	Power voltage
5~12	R0~R7	-	Red data
13~20	G0~G7	-	Green data
21~28	B0~B7	I	Blue data
29	GND	Р	Power ground
30	DCLK (CLK)	I	Pixel clock
31	DISP	I	Display on/off , normally pulled high
32	HEANC (HED)		Horizontal sync signal
32	HSYNC (HSD)	ı	If not used, fix this pin at VDD
33	VSYNC (VSD)	I	Vertical sync signal
	VOTNO (VOD)	'	If not used, fix this pin at VDD
34	DEN (DE)	I	Data enable (active High)
35	NC	-	No connect
36	GND	Р	Power ground
37	NC	-	No connect
38	NC	-	No connect
39	NC	-	No connect
40	NC	-	No connect

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9. Back Diagram:



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10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

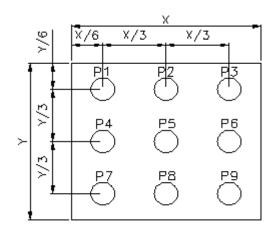
(Ta=25°C)

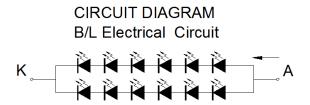
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Voltage	V	16.2	18.6	21.0	V	If=40mA	
Luminous Intensity for LCM	IV	300	350	-	Cd/m ²		2
Uniformity for LCM	1	70	1	-	%	If=40mA	3
Life Time	-	20000	-	-	Hr.		4
Color	White						

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Internal Circuit Diagram





(Effective spatial Distribution)

Using aperture of 1°, distance 50cm.

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11. Standard Specification for Reliability .: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : $10\text{Hz} \sim 55\text{Hz}$ Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: ± 6 KV 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 4KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs

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11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 12.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to **ISO2859-1.**General Inspection Level Ⅱ take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65% Minor defect: AQL = 2.5% Total defects: AQL = 2.5%

12-3. Non- conforming Analysis & Deal With Manners

- a. Non-conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

12-4. Agreement items

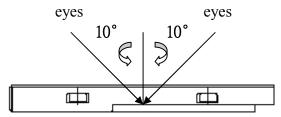
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

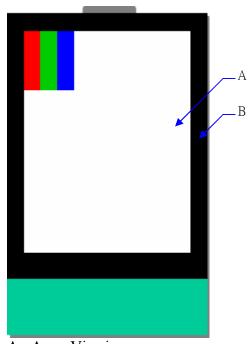
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- 12-5. Standard of The Product Appearance Test
 - a. Manner of appearance test:
 - (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)
- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

			CII	terion		AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 			0.65	
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 Dot dimension as be $\Phi = (X+Y)/2$ $X \qquad Y \qquad Y$ 2.2 Not visible through * Densely	5% ND file	Size(mm) $\Phi \le 0.20$ $0.20 < \Phi \le 0.40$ $0.40 < \Phi$	Acceptable Q'ty Accept no dense 5 0	2.5
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As fold $\Phi = (X+Y)/2$ * Densely 3.2 Line type: (As follow)	y spaced: Nowing drawing drawing drawing drawing drawing drawing L≤10 L≤10 L>10	ving $\frac{\text{Size(mm)}}{\Phi \leq 0.20}$ $0.20 < \Phi \leq 0.40$ $0.40 < \Phi$ $\frac{\text{So more than twing)}}{\text{Width(mm)}}$ $W \leq 0.1$ $0.1 < W \leq 0.25$ $$ $0.25 < W$	Acceptable Q'ty Accept no dense 5 0 ro spots within 3mm. Acceptable Q'ty Accept no dense 4 Rejection Rejection vo lines within 3mm.	2.5



NO	Item	Criterion			AQL	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction		Size Φ(mm) $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ 1.00 < Φ Total Q'ty		
05	Scratches	Follow NO.3 -2 Line T		•		
06	Mura	Not visible through 5%	ND filter in	50% gray.		2.5
07	Chipped glass	k: Seal width L: Electrode pad length 7.1 General glass chip: 7.1.1 Chip on panel surface z : Chip thickness $z \le 1/2t$ $1/2t < z \le 2t$ ① Unit: mm ② If there are 2 or more 7.1.2 Corner crack:	Chip width Not over via area Not exceed Chip width Not over via area Not over via area Not over via area Not over via	x: Chi ewing x: Chi ewing x: 1/3k x: Chi ewing x: 1/3k	ide length Is: $p \text{ length}$ $\leq 1/8a$ of each chip $p \text{ length}$ $\leq 1/8a$ $\leq 1/8a$	2.5



$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	
$y \leq 0.5 \text{mm} \qquad x \leq 1/8 \text{a} \qquad 0 < z \leq t$ $8.1.2$ Non-conductive portion:	
8.1.2 Non-conductive portion:	
Non-conductive portion:	
OS Class areals V	
W. Chin width W. Chin longth Z: Chip	2.5
y: Chip width x: Chip length thickness	
$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$	
 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment must mot be damaged. 8.1.3 Substrate protuberance and internal crack 	
y: width x: length	
$y \le 1/3L$ $X \le a$	



NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	 10.1 Illumination source flickers when lit. 10.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 10.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	 12.1 COB seal may not have pinholes larger than 0.2mm or contamination. 12.2 COB seal surface may not have pinholes through to the IC. 12.3 The height of the COB should not exceed the height indicated in the assembly diagram. 12.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 12.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 12.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
13	FPC	13.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 13.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
14	Soldering	14.1 No cold solder joints, missing solder connections, oxidation or icicle.14.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion			
	TO III	Symbols: x: Chip length k: Seal width length L: Electrode pad length 15.1 General glass cl 15.1.1 Chip on panel	y: Chip width z: t: Touch Panel Total t		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z. Cimp unexness		A. emp lengur	
15	Touch Panel	Z≦t	$\leq 1/2$ k and not over viewing area	x≤1/8a	2.5
13	Chipped glass	 ⊙ Unit: mm ⊙ If there are 2 or m 15.1.2 Corner crack: 	nore chips, x is the total	length of each chip	
		z: Chip thickness	y: Chip width	x: Chip length	
		z≦t	≤1/2 k and not over viewing area	x≤1/8a	
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip	•



NO	Item	Criterion		
16	Touch Panel(Fish eye)	$\begin{array}{ c c c c }\hline SIZE(mm) & Acceptable Q'ty \\ \hline L \leq 0.7 & Accept no dense \\ \hline L > 0.7mm & 0 \\ \hline \end{array}$	2.5	
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5	
18	Touch Panel Linearity	Less than 2.5% is acceptable.		
19	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		
20	General appearance	 20.1 Pin type must match type in specification sheet. 20.2 LCD pin loose or missing pins. 20.3 Product packaging must the same as specified on packaging specification sheet. 20.4 Product dimension and structure must conform to product specification sheet. 		



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment. YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.

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